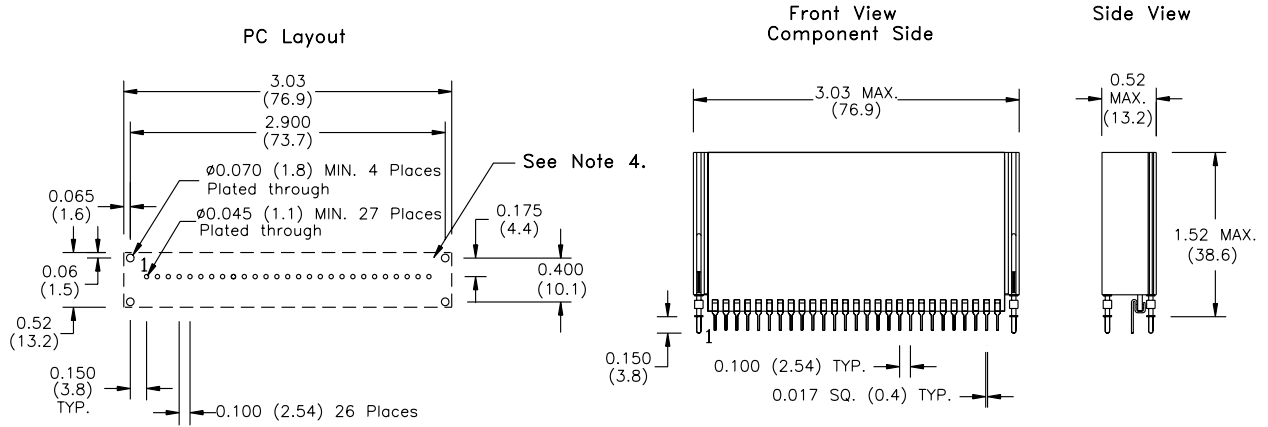


PACKAGE INFORMATION AND DIMENSIONS

Vertical Through-Hole Mount (Suffix N)

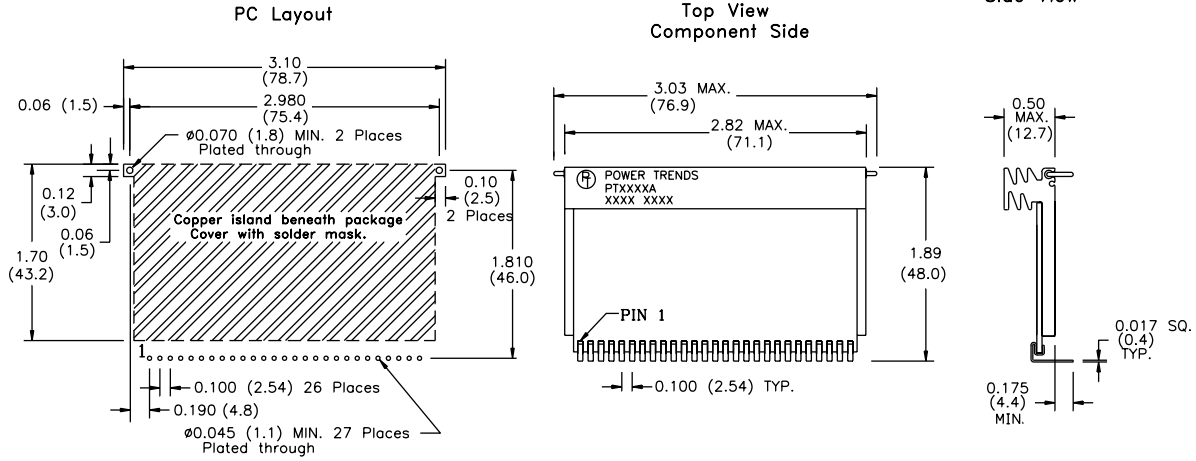


Notes: (Rev. C)

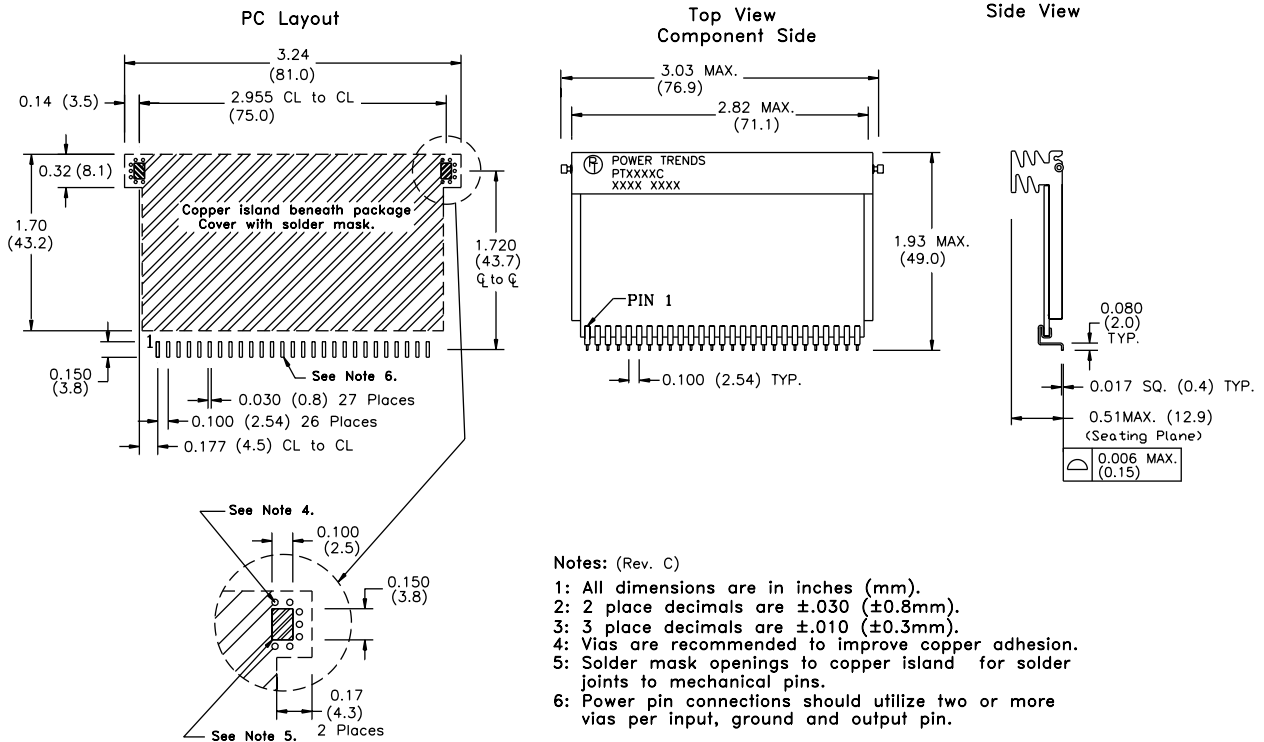
- 1: Dimensions are in inches (mm).
- 2: 2 place decimals are ± 0.030 (± 0.8 mm).
- 3: 3 place decimals are ± 0.010 (± 0.3 mm).
- 4: Recommended mechanical keep out area.

PACKAGE INFORMATION AND DIMENSIONS

Horizontal Through-Hole Mount (Suffix A)



Surface Mount (Suffix C)



Notes: (Rev. C)

- 1: All dimensions are in inches (mm).
- 2: 2 place decimals are ± 0.030 (± 0.8 mm).
- 3: 3 place decimals are ± 0.010 (± 0.3 mm).
- 4: Vias are recommended to improve copper adhesion.
- 5: Solder mask openings to copper island for solder joints to mechanical pins.
- 6: Power pin connections should utilize two or more vias per input, ground and output pin.